

2026 International Conference on Electronics Packaging and Hybrid Bonding Symposium (ICEP-HBS 2026)

**Hiroshima, Japan
14-18 April 2026**

IEEE Catalog Number:
ISBN:

CFP2689U-POD
979-8-3195-0588-0



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IEEE Catalog Number:	CFP2689U-POD
ISBN (Print-On-Demand):	979-8-3195-0588-0
ISBN (Online):	978-4-9914-8351-6

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TABLE OF CONTENTS

Testing and Characterization for Semiconductor Packaging Thermal Management	1
<i>Dongkai Shangguan, Chun Keang Ooi, Sze Pei Lim</i>	
Benchmarking AOI Capabilities for Fine Pitch Substrate Inspection	3
<i>Feng Xue, Charles Reynolds, Glenn Pomerantz, Jason Frankel, Thomas Wassick, Charlie Zhu</i>	
<i>Masahiro Tsuruya</i>	
Thermal Stress Study of Low Temperature Material for 1st Level Interconnect	5
<i>Sze Pei Lim, Danyang Zheng, Russell Kastberg, Shripad Gokhale, Masaki Sanada, Takumi Miyazaki</i>	
<i>Kei Murayama, Masahiro Tsuruya</i>	
Warpage Experiments and Simulation for Glass Core Substrate	7
<i>Kang Eu Ong, Junko Konishi, Yoichiro Sato, Tatsuro Yoshida, Kei Murayama, Makoto Tsukahara</i>	
<i>Haley Fu</i>	
Development of Automotive Chiplet SoC	9
<i>Nobuaki Kawahara</i>	
Compact FT-NIR spectrometer made through MOEMS technology for industrial applications	11
<i>Tomofumi Suzuki, Mizuki Fujiwara, Takuma Osaki, Shinichi Yoshii, Katsumi Shibayama</i>	
Advanced Panel Level Fan-out Package: Development of a Damascene Integration Scheme for Cu Redistribution Layers	13
<i>Eungchul Kim, Suhyeon Jeon, Jeongmin Seo, Takuya Nakagawa, Yuta Kimura, Dongjoon Oh, Juil Choi</i>	
<i>Minwoo Rhee</i>	
From Pilot To HVM: A Practical Overlay Yield Prediction Workflow For FOPLP Lithography	15
<i>John Chang, Jian Lu, Timothy Chang</i>	
TRC and Fusing current Characterization of Cu RDL Lines for Fan-Out Wafer-Level Packaging	17
<i>Fayong Liu, Jinbiao Hu, I-Hung Lin, Maple Jiang, Jinyan Nan, Ryan Pang, Dongdong Niu, Yinhan Zhao</i>	
<i>Qianyu Jia, Kaidi Sun, Haiyong Zheng, Tom Ni</i>	
Approach of graphic dynamic adjustment integrate to Laser direct imaging solution on 600mm Panel Fan Out	19
<i>Ping-Ching Shen, Sheng-Feng Huang, Ping-Feng Yang, Jen-Kuang Fang</i>	
A Novel Fan-Out Wafer Module Stacking Technology Using Transfer Bonding	21
<i>Chih-Cheng Hsiao, Chao-Kai Hsu, Chiao-Yen Wang, Yu-Lun Liu, Chin-Hung Wang, Wei-Chung Lo</i>	
<i>Kuan-Neng Chen, Shih-Chieh Chang</i>	
Warpage Prediction in Multi-Layer Fan-Out Panel-Level Packaging Using Finite Element Method with Artificial Neural Network	23
<i>Chen-Chen Li, Kuo-Shen Chen</i>	
New Advanced Packaging Architecture: CoWoP (Chip on Wafer on Platform PCB)	25
<i>Terry Hsu, HueiChi Yang, Ming-Han Zhuang, Sam Lin, Vito Lin, Andrew Kang, Don Son Jiang</i>	
Simplified Gap-Filling Process for Reconstructed Die-to-Wafer Hybrid Bonding Using Spin-Coated Silicone Resin	27
<i>Asuka Fujii, Yutetsu Kamiya, Kenta Hayama, Yuta Noguchi, Miharuru Kikuchi, Fumihiko Inoue</i>	

Prediction of High-Temperature Expansion of Cu in SiO ₂ Vias for Fine-Pitch Hybrid Bonding 3D-IC Applications	29
<i>Pin-Lin Chen, Chih Chen</i>	
Investigating Interfacial Reactions and Shear Strength of SnAg / Fe-HEA Alloy	31
<i>Tzu-Hsiang Liao, Jia-Xiang Gao, Chih-Hsiang Liu, Chuan Zhang, Yu-An Shen</i>	
Development and Characterization of Eco-Friendly Sn–Ag–Cu–Zn Solder for Electrical Performance on PCB Applications	33
<i>M. Ramanda Putra, Andromeda Dwi Laksono, Nurkholis Majid, Muhammad Mahessa Ajibasa Syaiban Devit Velanri Putra, Lusi Ernawati, Muhammad Ridho Dewanto, Kharis Sugiarto</i>	
Electro-Plating of Sn-Cu-Ni Based IMC Material for Connectors and Switches	35
<i>Hiroaki Ikeda, Shigenobu Sekine</i>	
Cu ₃ Sn as a Passivation Layer for Improving Reliabilities of Nanotwinned Cu Interconnects	37
<i>Jing Chok, Yi-Quan Lin, Chih Chen</i>	
Strengthening of Pressureless Ag Sintering with (111)-Oriented Nanotwinned Cu Substrate	39
<i>Shubo Ai, Xingming Huang, Zhi-Quan Liu</i>	
Electric Current Becomes a Thermodynamic Variable – Revisiting Phase Stability in Alloys	41
<i>Shubhayan Mukherjee, Shih-Kang Lin</i>	
Ultra-Thick Photoresist Patterning Enabling Higher Aspect Ratio Cu Posts for Advanced Packaging	43
<i>Tatsuya Fujii, Issei Suzuki, Kazuki Hirano, Eiichi Hayashi, Nobuya Takahashi, Toshiki Furutani Takashi Kariya</i>	
Investigation of SiCN-SiCN bonding with different wet pretreatment solutions followed by O ₂ plasma for hybrid bonding application	45
<i>Chien-Yu Liu, Pin-Syuan He, Yun-Hsuan Chen, Rou-Jun Lee, Gyanyu Song, Cheng-Chieh Kao, Chih Chen</i>	
Reliability Study of NMP-Free PI with Anti-Metal Migration Properties	47
<i>Han-Gung Chen, Wei-Chun Chen, Renata Hsiao, Fenny Liu, Allen Huang, Liang-Yih Hung, Andrew Kang</i>	
Fine Trench Fabrication by Excimer Laser Ablation and Plasma Etching	49
<i>Kento Eguchi, Masatsugu Nakano, Eiichiro Yamasaki</i>	
Proposal of Development of Megawatt Super-Power Operational Amplifier Using Distar Transistor	51
<i>Ken-Ichiro Okamoto, Kazunori Morishita, Kensho Okamoto, Atsushi Okuno</i>	
Microstructure Evolution and Strength Improvement in Cu-to-Cu Bonding with Micro/Nano Cu Paste	53
<i>Albert T. Wu, Li-Chen Wu, Shao-Chi Chen, Kelvin Li, Chang-Meng Wang</i>	
Via-Last Bumpless TSV for High Bandwidth NAND (HBN)	55
<i>Koji Sakui, Norio Chujo, Masao Taguchi, Takayuki Ohba</i>	
Localized plastic strain analysis of polymer films for fordable substrates using micro-digital image correlation	57
<i>Nakyung Jeong, Jeehoo Na, Eunhye Lee, Sojeong Lee, Tae-Ik Lee</i>	
High-Resolution 3D Printed Microelectronics Platform for Advanced Packaging Applications	59
<i>Darragh R. Walsh, Sophie C.E. Suijdendorp, Peter Rensing, Jeroen A.H.P. Sol, Hylke B. Akkerman</i>	

Investigation of Laser Parameters for the Creation of Traces and Contact Pads on Aluminum Nitride Ceramics	61
<i>F.-M. Deckert, C. Kleinholz, C. Heinze, M. Kermann, I. K��pplinger, T. Ortlepp</i>	
Analysis of Shrinkage-Induced Dimensional Mismatch in 3D-Printed Packaging Substrates for Flip-Chip Bonding	63
<i>Haksoon Jung, Yurim Choi, Kyungsun Kim, Nahyeon Kim, Jimin Kwon</i>	
Glasses as substrates for packaging: Remarks on Mechanic Reliability connected to via-via distance and via density	65
<i>M.Letz, H.Kanda, V.Seibert, F.Wagner, I.Burger, V.Glaser, V.Seibert, C.Schmucker</i>	
From Via to Singulation: Laser Technologies Driving Glass-Based Advanced Packaging	67
<i>Nils Anspach, Jannis Heinz, Daniel Dunker, Norbert Ambrosius, Simon Hirt, Roman Ostholt</i>	
Reliability Evaluation of 40 μm -Pitch Solder Joint on Glass Interposer	69
<i>Naoko Katoh, Sayuri Kohara, Toyohiro Aoki, Chinami Marushima, Koki Nakamura, Hiroyuki Mori Akihiro Horibe</i>	
Next Generation High Energy Efficiency Packaging Study	71
<i>Henry H. Utsunomiya, Hiroshi Iinaga, Hirohiko Matsuzawa</i>	
Evolution of Wafer Level Packaging Roadmap: Technical and Structural Advancements Toward Heterogeneous Integration	73
<i>Farhang Yazdani, Rozalia Beica, Bilal Hachemi</i>	
An Experience-Driven Advanced Digital Lithography System for Panel Applications	77
<i>Yusuke Matsushashi, Tomomi Terada, Koichi Bito, Masaki Kato, Kazuya Okamoto</i>	
Considerations for Implementing CMP in Panel-Level Packaging	79
<i>Haedo Jeong</i>	
EDA Solution for Chiplet and 3D-IC Design	81
<i>Ksenia Roze, Mark Gerber</i>	
Effect of Moisture on the Reliability of Advanced Packaging	83
<i>Hyunmin Park, Wonbin Kim, Yoon-Gu Lee, Yoon Lee, Byoung-Joon Kim, Young-Chang Joo</i>	
Novel Electrochemical Processes for Advanced Packaging	85
<i>Bongyoung Yoo</i>	
Visualization of Corrosion in Electrodes Using a Conditional Diffusion Model Trained on S-Parameters	87
<i>Haebom Lee, Tae Yeob Kang</i>	
Clustering-Enhanced Deep Surrogate Model for Global Stress and Weak-Point Detection in Semiconductor Packaging	89
<i>Boo Soo Ma, Boyeon Kim, Myoung Song, Tae Yeob Kang, Taek-Soo Kim</i>	
Glass/LTCC Composite Substrates as Completely Inorganic Packaging Interposer	91
<i>Jens Mueller, Mahsa Kaltwasser, Heike Bartsch, Michael Fischer</i>	
Robust Ceramic Components and Packages for Modern Lithography Systems	93
<i>M. Eberstein</i>	

Precision Laser Ablation for Conformal Coating Patterning/Rework in High-Reliability PCBs	95
<i>Markus Bohrer, Shantanu Sangam, Eklavya Koshta</i>	
Si-based optical interface devices for photonics electronics convergence technology	97
<i>Hideki Gotoh, Sangmin Ji</i>	
SiC CMOS Integrated Circuits and Image Sensors for Extreme Environment Applications	99
<i>Shin-Ichiro Kuroki</i>	
Feasibility study of laterally embedded ceramic inlays into silicon substrates for sensor applications	101
<i>M. Fischer, C. Kleinholz, A. Schulz, B. Müller, J. Müller</i>	
Silicon-on-Ceramic: An Innovative Technology Platform	103
<i>C. Kleinholz, B. Müller, M. Fischer, A. Schulz, A. Cyriax, M. Hintz, T. Ortlepp, J. Müller</i>	
Fabrication and Evaluation of Fully Embedded Silicon Strain Gauges in Ceramic Material for Wet-Wet Applications	105
<i>C. Kleinholz, T. Frank, A. Cyriax, S. Jagomast, C. Maier, M. Hintz, A. Schroeter, U. Krieger, T. Ortlepp</i>	
A Process-Chemistry Map for Room-Temperature Dielectric Bonding	107
<i>Yun-Hsuan Chen, Guanyu Song, Cheng-Chieh Kao, Chih Chen</i>	
A Comparison Study on Room Temperature Bonding of Sapphire-Sapphire and Al ₂ O ₃ Film-Al ₂ O ₃ Film	109
<i>K. Uno, R. Takigawa</i>	
Study on Surface Uniformity Improvement of Ag Nanolayer Formed by Galvanic Deposition	111
<i>Quan-Wei Yip, Cheng-Min Yen, Shih-Kang Lin</i>	
Heterogeneous Integration of LiNbO ₃ and Si Dies Using Room-Temperature Au-Au Bonding in Ambient Air With O ₂ Plasma Treatment	113
<i>K. Matsunobu, R. Takigawa</i>	
Heterogeneous Device Structure without Underfill Connected with Submicron Gold Particle Bump and Seal by Chip on Wafer Process	115
<i>T. Imahigashi, S. Tsukahara, A. Yoshida, T. Asakawa, T. Tsutsumi</i>	
Design for Functional Resin Filling Process for Direct Nanoimprint Lithography	117
<i>R. Yamamura, A. Mochida, D. Sakurai, M. Yasuda, Y. Hirai</i>	
Fine-pitch Copper Wiring Formation on Build-up Film fabricated by Silver-seed Semi-Additive Process	119
<i>Wataru Fujikawa, Akira Murakawa, Shota Niibayashi, Akinori Furutani, Rei Tamura, Norimasa Fukazawa</i>	
Study on the Blind Via Hole Metallization Method for High-Speed Transmission Using Hybrid Desmear and High-Reliability Electroless Copper Plating	121
<i>T. Sawada, Y. Kitahara, Y. Baba, T. Arimoto, T. Koga</i>	
Interfacial Reactions in the Cu/Sn/Ni Sandwich Couples in 3D IC Packaging	123
<i>Yen-Ling Chen, Yi-Pin Lin, Shih-Jung Chai, Yee-Wen Yen</i>	
Optimization of Encapsulation process for Advanced package using simulation	125
<i>Kazuki Noguchi, Joseph Liang, Sean Wang, Masaharu Kataoka, Hirofumi Torigoe, Leo Shen</i>	
Accurate identification of submicron-sized particle on a copper substrate	127
<i>Michael K. F. Lo, Naoki Baden</i>	

A mixed crystal structure for the investigation of Cu-Cu bonding	129
<i>Shichen Xie, Zishan Xiong, Yingxia Liu</i>	
Impact of Surface Treatment Queue Time on Low-Temperature Nanocrystalline Cu Bonding	131
<i>Chen-Ning Li, Artur Kolics, Mengping Li, Shantinath Ghongadi, JaeHong Kim, Tien-Jen Cheng</i> <i>Cheng-Chieh Kao, Chih Chen</i>	
In-Sn Passivated Low Temperature and Low Pressure Cu-Cu Interconnects	133
<i>Y. H. Lu, P. S. Shih, W. C. Lee, C. Y. Yang, Y. C. Hung, Y. S. Lin, C. C. Wang, C. P. Hung, C. R. Kao</i>	
Reliability Assessment of Hybrid Bonding Interconnects under Electromigration Stress	135
<i>Min-Yan Tsai, Shan-Bo Wang, Yung-Sheng Lin, Yu-Jen Chang, Che-Ming Hsu, Chih-Jing Hsu</i> <i>Zhao-Ze Jiang, Chen-Chao Wang, Chih-Pin Hung</i>	
Enhanced electromigration resistance by nanotwinned Cu-Ag Interconnects for advanced packaging	137
<i>Fan-Yi Ouyang, Peng-Hsiang Hsu, Yung-Pei Lin</i>	
Characterization for the Bottom Joint of Stacked Micro-Via Integrated in the Substrate by ToF-SIMS and STEM	139
<i>Masahiko Nishijima, Ming-Chun Hsieh, Rieko Okumura, Hiroyoshi Yoshida, Chuntong Chen, Hiroki Seto</i> <i>Kei. Hashizume, Kimihiro Yamanaka, Hiroshi Nishikawa, Katsuaki Suganuma</i>	
Corrosion behavior of Cu-to-Cu direct bonding by refill friction stir spot welding for busbar application	141
<i>Ha-Young Yu, Myong-Gyu Lee, Jiyong Park, Dongjin Kim</i>	
Signal Integrity and Mechanical Design for Mounting HBM4 on an Organic Interposer	143
<i>Taishi Yamaguchi, Yuji Kunimoto, Haruki Horiuchi, Manabu Nakamura</i>	
Methods for Extracting the Electrical Characteristics of FC-BGA Packages under Thermal Conditions	145
<i>Aki Tanaka, Satoshi Nakamura</i>	
Method for Predicting the Impact of Manufacturing Variations Using S-Parameters	147
<i>Satoshi Nakamura, Aki Tanaka</i>	
Study on Acceleration of Preconditioning for Solderability Testing	149
<i>Takaaki Sensui, Hideyuki Nagai</i>	
Multiphysics Analysis of Magnetic Thin-Film Inductors	151
<i>Y.C.Chao, T.S.Chang, D.S.Liu</i>	
Systematically Optimized Ensemble Stacking Learning Framework for Process-Induced Warpage Prediction in SiC Power Modules	153
<i>Hsiang-Yu Hsu, Yang-Lun Liu, Hsien-Chie Cheng</i>	
Warpage Simulation Development for PCB Packaging in AI Drives under Reliability Conditions	155
<i>Shifa Zehraddin Desai, Yan-Yu Liou, Ming-Chang Wu, Chen-Chou Tsai, Chieh-Yu Ma, Xi-Hong Chen</i> <i>Chih-Cheng Tsai, Wen-Chen Wu, Chang-Chun Lee</i>	
Development of a High-Resolution, High-Reliability Photo-Imageable Dielectric	157
<i>Kohei Abe, Ryo Yukioka, Takeshi Nojiri, Emi Miyazawa, Takashi Kawamori</i>	
Low-temperature Sintering Accelerating of Silver Micro-flake for Improving Interconnect Characteristics by Designing Aliphatic Epoxy-based Binder	159
<i>T. Fukushima, M. Inoue</i>	

Morphology and Electrical Resistivity of Pyrolyzed Carbon Micro-architectures	161
<i>Yu-Yen Chen, Hiroaki Tatsumi, Hiroshi Nishikawa</i>	
Stretchable PEDOT: PSS Films with Enhanced Electrical and Mechanical Properties for Printed Electronics	163
<i>Masahiro Inoue, Hideyo Shimizu</i>	
Low-Temperature Sintering of Cu Microparticle/CuXO Nanoparticle Composite Pastes for High-Strength Bonding	165
<i>Tetsu Yonezawa, Takashi Aso</i>	
Octylamine-Assisted Copper Metal–Organic Decomposition Ink for Low-Temperature Sintering	168
<i>Yi Zheng, Hiroki Tsukamoto, Tetsu Yonezawa</i>	
High-Strength Cu Joint Fabricated Using Bimodal-Sized Cu Nanoparticles	170
<i>Qianhao Zuo, Tetsu Yonezawa</i>	
Surface Modification of Fine Grain Copper for Low Temperature Hybrid Bonding	172
<i>Taiki Miyamoto, Kenta Hayama, Fabiana Lie Tanaka, Yutetsu Kamiya, Marie Sano, Ryota Naka Ryo Tanaka, Fumihiko Inoue</i>	
Influence of Indium on the Strength, Ductility and Soldering Behavior of Sn-Bi Alloys on Copper	174
<i>Chih-Hsiang Liu, Tzu-Hsiang Liao, Jia-Xiang Gao, Yu An Shen</i>	
Minor Indium Additions to Sn-Bi Alloys - Properties and Corrosion	176
<i>Jia-Xiang Gao, Chih-Hsiang Liu, Tzu-Hsiang Liao, Yu-An Shen</i>	
Microstructural Refinement and Solidification Behavior in Sn-In Composite Solders with NiO-Coated ZrO ₂ Nanoparticles	178
<i>Shunya Nitta, Hiroaki Tatsumi, Atsushi Ito, Arimichi Takayama, Hiroshi Nishikawa</i>	
In-situ observation of BiIn ₂ (Sn) dissolution in low temperature In-Sn-Bi alloys	180
<i>Jiye Zhou, Xin Fu Tan, Stuart D. McDonald, Kazuhiro Nogita</i>	
Tensile properties of Sn-37Bi-0.5Sb-0.5Cu-0.03Ni low-temperature soldering alloy	182
<i>Xiaozhou Ye, Stuart D McDonald, Xin Fu Tan, Takatoshi Nishimura, Keith Sweatman, Kazuhiro Nogita</i>	
In-situ SEM Investigation of Tensile Deformation of Various Sn-xBi Solder Alloys	184
<i>Y. H. Yen, Y. S. Lin, C. R. Kao</i>	
Effect of Sb Addition on the Tensile and Creep Properties of Sn–(58-x)Bi–xSb Low-Temperature Solders	186
<i>Zhi-Chen Ai, Yu-Chen Liu</i>	
Machine Learning-Based Prediction of Electromigration-Induced Resistance Change in Sn-Bi Low-Temperature Solders	188
<i>Chi Chen, Yu-Chen Liu</i>	
High thermal conductive composite for efficient heat spreading through multi-dimensional strategy	190
<i>Bin Xu, Junichiro Shiomi</i>	
Ag-coated Ni Metallization for Fluxless Indium-Based TIM Bonding	192
<i>Y. H. Ku, C. Y. Yang, Y. H. Lu, C. R. Kao</i>	

Thermal properties of Vertically Aligned Carbon Nanotube-based Thermal Interface Materials	194
<i>Yoku Inoue, Tomoki Okumura, Yamato Watanabe, Takayuki Nakano</i>	
Room Temperature Direct InP/SiC Bonding via SAB For Improved Thermal Performance	196
<i>J. Nakamura, R. Takigawa</i>	
Development of high heat dissipation insulated metal substrates using thin insulating films	198
<i>K. Ono, M. Nishimura, K. Usami, Y. Watanabe, Y. Yanase, Y. Takagi, K. Takagi, A. Hattori</i>	
On the Temperature Measurement of on-state GaN-HEMT by Raman Spectroscopy	200
<i>K. Sagawa, K. Kobashi, S-M. Chen, T. Hoshii, A. Myalitsin, H. Ryoson, T. Yoda, T. Ohba, K. Kakushima</i>	
Investigation of Thermal Transient Measurement Methods of Cascode GaN HEMT Devices	202
<i>Wasanthamala Badalawa, Yoshitaka Aoki</i>	
A New Thermal Conductivity Measurement Methodology	204
<i>Tomoaki Hara, Qun Yuan, Haifeng Xu, Shigeru Kondo, Shuhei Fukunaga, Tsuyoshi Funaki</i>	
Investigating the Thermal Resistance of the Si and Epoxy Interface	206
<i>Wei Cheng Huang, Lev Tseng, Bo Yu Huang, Meng Hsueh Yang, Hui Chung Liu</i>	
Cooling Performance Improvement of Heat Sinks by Utilizing Thermal Impedance Distribution	208
<i>K. Nishi</i>	
From Package to Power Integration: Enhancing Energy Efficiency through Improved Thermal Dissipation	210
<i>Che-Sheng Kung, Hao-Yu Lu</i>	
Design and Evaluation of Microchannel Cooling Modules for 2.5D Multi-Hotspot High-Power Packages	212
<i>Yu-Hao Lo, Jun Mizuno, Hsuan-Hao Chang, Yu-Ting Wu, Muhammad Firman Friyadi, Chi-Hua Yu Takeshi Miyamoto, Wen-Chun Wu, Hung-Hsien Huang, Chen-Chao Wang, Chih-Pin Hung</i>	
Maximized manufacturing flexibility and convective heat transfer characteristics of direct cooling method for use in large-area power electronics heat sink	214
<i>Byeong Chan, Ha-Young Yu, Junha Baik, Dongjin Kim</i>	
Effect of Thermal Properties of Dielectric Liquids on Breathing Phenomenon Induced by Lotus-Type Porous Copper	216
<i>T. Okafuji, T. Ide, K. Yuki, T. Ogushi, M. Murakami, Y. Shiraishi, M. Thomson, K. Yuki</i>	
Diamond Thermal Solutions for Emerging High-Heat-Flux and High-Power Semiconductor Packaging	218
<i>Yonhua Tzeng, Chun-Ping Lin, Ci-Jhen Fu, I-Lun Chiu, Ying-Yuan Huang, Pai-Chun Wei, Han-Ying Chen Kueifeng Chiang</i>	
Integrating Solutions for Advanced Packaging Complexity	220
<i>Shin-Puu Jeng</i>	
Fine/coarse-grained Composite Structure for Cu-Cu Direct Bonding	222
<i>Hsiang-Yu Wei, Chih-Ming Chen</i>	
Enabling Next Generation Packaging with Glass and Quartz Core Substrates	224
<i>J. Discher, C. Wesselkamp, L.Hofmann</i>	

Glass Core Evaluation & Testing Method	226
<i>Ming-Yi Tsai, T.Onishi T. Onishi, J.Harada</i>	
Development of glass core multilayer build-up substrate with TGV	228
<i>Jun Yoshiike, Masahiro Sunohara, Gai Kadoishi, Yoko Nakabayashi, Noriyoshi Shimizu, Ryuichi Matsuki</i>	
Physical Estimation for Residual Stress of Glass Substrate through Photoelasticity-FEA Hybrid Model	230
<i>Jui-Chang Chuang, Chang-Chun Lee, Wan Chen Yang, Po-Yu Chen, Hao-Zhou Lin, Wei-Cheng Tsai</i> <i>Chen-Tsai Yang, Man-Ning Lu, Po-Chi Sung, Wei-Chung Wang</i>	
Micro-crack-free Laser Singulation and meltingTGV for Glass Substrate	232
<i>Eunsuk Jeon, Jinpyo, Duhyun Cho</i>	
Analysis of Fracture Mechanism During the Dicing Process of Glass Substrates	234
<i>Jingyi Zhao, Quanlu Zhao, Chuan Chen, Qidong Wang, Xiaomeng Wu, Qichang An</i>	
Low-temperature copper sinter-joining technology for next-generation electronics	236
<i>Xinyi Shi, Ningxi Zhang, Yujian Wang, Wanli Li</i>	
Advancements in Ultra-High Aspect Ratio Via Interconnection Technology Enabled by Atomic Layer Deposition	238
<i>Ke Li, Yi Zhong, Daquan Yu</i>	
The Simulation and Testing of UCle Power Noise Based on Chiplet	240
<i>Zhijun Long, Chenxi Yang, Jianguo Zhang, Bin Yu, Guanghao Zeng, GuangYao Li, KeQing Ouyang</i>	
Optical Chiplet Using Membrane III-V Photonic Devices	242
<i>S. Yamaoka, T. Hiraki, T. Minotani, Y. Shikama, T. Aihara, T. Fujii, Y. Maeda, N. Sato, T. Sato, S. Matsuo</i>	
Reliability Evaluation of Copper Pin Package-on-Package Structures for Co-Packaged Optics	244
<i>Motoyuki Fukuhara, Tatsuki Denda, Masaki Matsumoto, Futoshi Tsukada, Noritaka Katagiri</i>	
Thermal Analysis and Demonstration of Mirror-based Optical Redistribution Layer for Co-packaged Optics	246
<i>Fumi Nakamura, Satoshi Suda, Takayuki Kurosu, Akihiro Noriki, Takeru Amano</i>	
High-Precision Passive Alignment for Multi-Channel Optical Connections in Silicon Photonic Microtransceivers	248
<i>Michiyo Kubo, Shigeru Kobayashi, Koichi Takemura, Kazuhiko Kurata</i>	
Low Temperature Hybrid Bonding Process by Surface Modification using Low-Molecular-Weight Organic Material	250
<i>C. Nakagawa, Y. Ohmukai, K. Hosoda, Y. Araga, N. Watanabe, H. Shimamoto, K. Takahashi, T. Namikawa</i> <i>K. Kikuchi</i>	
In-situ Analysis of SiO ₂ Surface Chemistry Evolution During N ₂ Annealing for Hybrid Bonding Applications	252
<i>Haibo Yang, Fei Ding, Yu Zhang, Yudong Yang, Qiushi Kang, Yihao Meng, Renxi Jin, Liqiang Cao</i> <i>Qidong Wang</i>	
High-Resolution 3D X-Ray Imaging of Hybrid Bonding	254
<i>Till Dreier, Daniel Nilsson, Shiho Tanaka</i>	
Development of Anti-oxidation Technology for Cu Direct Bonding via Ascorbic Acid Vapor	256
<i>Jeeshoo Na, Eunhye Lee, Suin Jang, Dongwoo Lee, Tae-Ik Lee</i>	

Electrodeposition of (111)-Oriented Cu Using Accelerator for Cu–Cu Direct Bonding	258
<i>Soojin Kim, Jungjoon Park, Haneul Han, Jinmyeong Seo, SangHwa Yoon, Bongyoung Yoo</i>	
Effect of Pressure on Grain Growth in Nanocrystalline Cu for Low-Temperature Cu-Cu Bonding	260
<i>Ting-Chi Chen, Chih Chen</i>	
Establishment of High-Yield and Reliable Cu-Cu Connections with 0.8 μm Pitch Integration	262
<i>Hitomi Shiina, Yukako Ikegami, Ken Arano, Kan Shimizu, Yoshihisa Kagawa</i>	
Copper oxide in TCB Cu-Cu bonding	264
<i>Kun-Yuan Zeng, Yu-hao Chou, Shih-Kang Lin</i>	
Surface Reduction and Self-Passivation in a Single-Step Ar/CH ₄ Plasma treatment for Hybrid Cu Bonding	266
<i>Hoogwan Lee, Byeongchan Go, Jeongmin Park, Sarah Eunkyung Kim</i>	
Advancing Cu-Cu Direct Bonding Through Optimized Surface Treatment Strategies	268
<i>K. Kondracka, C. Sébert, P. Verdonck, K. Wouters, N. Kuznetsova, P. Merken, I. Taurino, M. Kraft</i>	
Mixed-Foundry Heterogeneous Integration of Bumpless WOW and COW Processes for System-on-Wafer	270
<i>Norio Chujo, Shinji Sugatani, Tadashi Fukuda, Takayuki Ohba</i>	
Develop Three-Dimensional Infinite Element Method of Thermal Stress for Through-Silicon Via Analysis	272
<i>D. S. Liu, W. H. Chang, T. S. Chang, Z. W. Zhuang, Y. C. Chao, P. C. Huang</i>	
Physical Estimation of Epoxy Flux Pattern Design of Multi-Chip Module Packaging	274
<i>Kuan-Wei Chou, Chih-Yang Weng, You-Yi Zheng, Shen-Yu Yang, Chao-Chieh Chan, Chun-Wei Wang</i> <i>Jui-Chang Chuang, Chang-Chun Lee</i>	
Simulation of NSMD Type in CUF Parameters and Substrates on Reliability	276
<i>Tzu Chieh Chien, Yuan Hung Sun, Yu Chi Sung, Chao Lin Shih, Hui Chung Liu, Lu Ming Lai</i> <i>Ying Zhong Chen, Kuang Hsiung Chen</i>	
Capillary Underfill Simulation across Die-to-Die Gap Using Hybrid EBG Modeling	278
<i>Leo Shen, Kazuki Noguchi, Yu-En Liang, Wei-Yu Lin, Zi-Hsuan Wei, Ching-Kai Chou, Ming-Yu Lin</i>	
Numerical Simulation and Machine Learning–Based Optimization of Mass Reflow Temperature Profiles in Batch-Produced System-in-Packages	280
<i>Ian Hu, Xuan-Zhi Kuo</i>	
In-situ observation of dislocation movement, accumulation and crack propagation during tensile loading in Sn and Sn-based solder alloys	282
<i>Kazuhiro Nogita, Jiye Zhou, Xin F. Tan, Stuart D. McDonald, Keith Sweatman, Hiroshi Maeno</i> <i>Syo Matsumura, Kazuhiro Yasuda</i>	
The role of densification on deformation behavior of sintered Ag during nanoindentation creep testing	284
<i>Seonghwan Park, Hiroaki Tatsumi, Hiroshi Nishikawa</i>	
Defects in Cu-filled through-silicon vias (TSV) after thermal cycling	286
<i>Zishan Xiong, Shichen Xie, Zeyuan Li, Zhaotian Li, Zhaofu Zhang, Sheng Liu, Yuzheng Guo, Yingxia Liu</i>	

Lifetime Prediction of Die Cracking in Heatsink-Clamped FCQFN Packages under Thermomechanical Loading	288
<i>Wei-quan Luo, Ke Xue, Lan-qin Huang, Kai Chen, Yunda Wang, Dong Lu</i>	
Thermal and Drop Reliability Performance of Low Temperature Solder in Fan-Out WLP structure	290
<i>Nien-Chun Lin, Chun-Yu Yen, Sheng-Hong Zheng, Yan-Bo Lin, Chih-Sheng Su, Hsin-Chih Shih Chin-Li Kao, Chen-Chao Wang, Chih-Ping Hung</i>	
Enhancement of Micro-DIC Technique and Deformation Measurement of Fine-Pitch Semiconductor Packages	292
<i>Hyunwoo Nam, Seongkyu Choi, Minjeong Sohn, Tae Yeob Kang, Tae-Ik Lee</i>	
Static Structural and Thermal Analysis of Heterogeneous 3D IC Integration Using Silicon and Glass Interposers	294
<i>Divyankar Jha, Sai Bharat Reddy, Ying-Chao Hsu</i>	
Pre-heating influence on thermo-mechanical response of Ag–Au–Pd alloy fine wire during wire bonding process	296
<i>P.-C. Huang, Z.-H. Xie, W.-L. Kao</i>	
A Compact Dual-Band AiP Integrated Beamforming IC Using Package-on-Package Technology for Mobile Devices	298
<i>Sheng-Chi Hsieh, Hong-Sheng Huang, Wen-Chun Hsiao, Chen-Chao Wang, Sheng-Ya Lin</i>	
Design of millimeter-wave antenna array in package featured with bandpass impedance transformation	300
<i>Si-Min Wang, Kuo-Hung Cheng, Sheng-Fu Chang, Shih-Cheng Lin, Chen-Chao Wang</i>	
Fabrication tolerance analysis of multi-layers package substrate for 5G mmWave Antenna in Package/Module (AiP/AiM)	302
<i>Cheng-Yu Ho, Huang Po-Ming, Yi-Ping Sun</i>	
Development of Integrated Q-band 4×4 Phased-Array Module with High Aspect Ratio Cu-Pillar Pins and M7-Level SLP for High-Efficiency mmWave NTN Applications	304
<i>Li-Cheng Shen, Wei-Yang Chen, Ming-Hung Chang, Leo Hsu, Su-Wei Chang, Chi-Hsin Hsu Chao-Hsuan Wang, Hung-Yi Tsai, Kuo-Hsien Liao</i>	
Comparison of Cu diffusion barrier properties of Electroless-plated CoWB and CoMn alloy films formed on SiO ₂ /Si	306
<i>S. Shingubara, T. Shimizu, T. Ito</i>	
Photon-removable Protective Molecular Nanolayers for Enhancing Cu to Cu Direct Bonding	308
<i>Wei-Ting Chen, Ting-Hsiang Hsueh, Chih-Ming Chen, Takafumi Fukushima, Jenn-Ming Song</i>	
Effect of Binder Chemistry on Dynamic Parcolation of Stretchable Printed Wires During Vacuum Forming	310
<i>Rina Aida, Masahiro Inoue</i>	
Advanced Hybrid Smear Removal Process with Excimer VUV Treatment for Next-Generation Organic Substrate Packaging	312
<i>T. Arimoto, Y. Baba, Y. Kitahara, T. Sawada, T. Katou, M. Kusunoki, T. Koga, Y.Y. Lim</i>	
Integrating Mechanical and Chemical Insights Into Bonding Interfaces via DCB-Based Delamination Analysis	314
<i>Shumpei Murakami, Yuki Yoshihara, Daiki Kobayashi, Ryuki Kusakabe, Marie Sano, Fumihiro Inoue</i>	

Quantitative Assessment of Bond Strength for Hybrid Bonding	316
<i>Ryuki Kusakabe, Daiki Kobayashi, Yuki Yoshihara, Shumpei Murakami, Marie Sano, Shunsuke Teranishi</i> <i>Yuya Matsuoka, Daichi Saito, Naoko Yamamoto, Fumihiro Inoue</i>	
Performance of Machine Learning Algorithms for Real-Time Temperature Measurement Using Optical-Interference Contactless Thermometry	318
<i>Jiawen Yu, Hiroaki Hanafusa, Seiichiro Higashi</i>	
Acoustic Emission Signal Filtering for Ultrasonic Vibration-Assisted Grinding Wheel Monitoring Using a Hydrophone Sensor	320
<i>Yu-Kun Lin</i>	
Development of Low-Temperature Air-Sinterable Copper Paste for Die Attach and Substrate-to-Heatsink Bonding	322
<i>Chuantong Chen, Fupeng Huo, Sangmin Lee, Takeshita Kazutaka, Yoshiji Yamaguchi, Yashima Momose</i> <i>Katsuaki Suganuma</i>	
Room Temperature Chip Bonding of SiC And Cu Using Activated Cu Atomic Layer	324
<i>R. Yamauchi, J. Utsumi, R. Takigawa</i>	
X-ray Orientation Microscopy for Non-destructive Observation of Grain Boundaries in Die-attach Solder	326
<i>Y. Hayashi, J. Kim, M. Yabashi, H. Tatsumi</i>	
Near-Chip 3D Functionalization of Direct Copper Bonded Substrates in Power Electronic Modules	328
<i>Christoph Hecht, Dominik Wiegand, Marcel Sippel, Jörg Franke, Manuela Ockel</i>	
Heatsink Design and Wire Bonding Failure Analysis of an Automotive 1.2 kV SiC MOSFET Power Module in Power Cycling Tests	330
<i>Po-Kai Chiu, Ji-Yuan Syu, Ting-Yu Wang, Yu-Hua Wu, Kuo-Shu Kao, Tao-Chih Chang</i>	
Reliability and Thermal Resistance Characterization of Flip-Chip Interconnections in Gallium Nitride Devices Using Silver Sintering Materials	332
<i>Ching Kuan Lee, Ting-Yu Ke, Chen-Lung Lin, Yi-Chan Yeh, Shu-Yi Chang, Chia-Jung Hsieh, Yu-Li Wu</i> <i>Hsiu-Kuei Ko, Yuan-Cheng Huang, Hsin-Han Lin, Yan-Cheng Liu, Chiu Po-Kai, Yu-Min Lin, Kuo-Shu Kao</i>	
Junction Temperature Estimation Error of Chip-Embedded Temperature Sensor During Transient Thermal Measurement	334
<i>Shuhei Fukunaga, Tsuyoshi Funaki</i>	
A Flip Chip Embedded PCB Power Module with Double Sided Cooling and Low Parasitic Inductance for Fine Pad Power Devices	336
<i>H. C. Kao, H. H. Lin, Y. C. Huang, P. K. Chiu, A. Y. Lin, C. L. Lin, W. H. Liu, Y. C. Yeh, H. K. Ko</i> <i>T. C. Chang</i>	
Atmospheric Pressure Plasma Processes for Metal Oxide Reduction and Adhesion Improvement in Power Electronics	338
<i>Hisanori Miyoshi, Dhia Bensalem, Nico Coenen, Yaser Hamedi, Magnus Buske, Daphne Pappas</i>	
A power semiconductor chip rework technology without thermal and mechanical processes	340
<i>Junha Baik, Byeongchan Kim, Ha-Young Yu, Myong-Gyu Lee, Dongjin Kim</i>	
Development of Equivalent Material Properties of Substrate/Interposer-type Components for Advanced Packaging	342
<i>Ya-Chi Chen, Yu-Ting Su, Kuo-Ning Chiang</i>	

Reliability Prediction of Wafer-Level Packaging under Small Sample Datasets Utilizing Adaptive Sampling	344
<i>C.H. Lo, K.N. Chiang</i>	
Towards a multi-agent-based diagnostic system for prescriptive maintenance applications in industrial environments	346
<i>Felix Mahr, Cathleen Kratzke, Jörg Franke, Manuela Ockel</i>	
Intelligent Troubleshooting System for SMT Manufacturing Using Web Scraping, GraphRAG and Knowledge Graphs	348
<i>Felix Mahr, Jörg Franke, Manuela Ockel</i>	
Experimental Study on the Forced Convection Effectiveness of a Double-Tube Thermal Module for Electronic Packaging	350
<i>C.M. Lai, C.J. Ho, R.H. Chen, S.H. Huang</i>	
Microstructural and Thermo-Mechanical Behavior of Cu–Al Bilayer Alloy for Low-Temperature Hybrid Bonding	352
<i>Sarabjot Singh, Kathleen Dunn</i>	
Latent Catalysts Development for Energy Saving Semiconductor Packaging Application	354
<i>Yi-Chun Chen, Chih-Hao Lin, Kai-Chi Chen</i>	
Prediction and Analysis of Bifurcation Warpage in Wafer Packaging based on Machine Learning	356
<i>Chi-Hsiang Su, Kuo-Shen Chen, Chen-Chen Lee, Ching-Jenq Ho</i>	
Feasibility and Reliability Considerations of Liquid Metal Alloys in Advanced Packaging	358
<i>Wen-Yu Teng, Dai Fei Li, Jyun-De Jhan, Yung Ta Li, Andrew Kang, Don-Son Jiang</i>	
Synthesis and characterization of thermally conductive carbon nanotube-reinforced polysiloxane composites	360
<i>Chih-Feng Wang, Fu-Cheng Tang, Pei-Rung Hung, Pei-Kang Huang, Ping-Feng Yang, Shiao-Wei Kuo</i>	
Development of A 650 V / 300 A GaN Half-bridge Power Module	362
<i>Yuto Kinoshita, Kotaro Okano, Shota Yamda, Tatsumi Yamamoto, Takeya Matsumoto, Eigo Fukuda, Takaharu Takeshita, Toshihiko Noguchi, Masato Omori</i>	
Surface smoothing based on Au film transfer for room-temperature GaN/diamond bonding in air	364
<i>Shintaro Goto, Shogo Koseki, Kai Takeuchi, Eiji Higurashi</i>	
Nanoindentation Investigation of Through Substrate Vias Drilled by Ultrashort Pulse Laser Percussion	366
<i>Ruenn-Bo Tsai, Sheng-Wei Tsai, Jhih-Syuan Jhan, Hsueh-Yi Hsiung, Po-Nien Su, Meng-I Huang, Bing-Ru Hsieh</i>	
Broadband Transition from Microstrip to Inverted Microstrip Gap Waveguide Using Via-Guards Copper Via	368
<i>Po-Kai Hsu, Ruenn-Bo Tsai, I-Yu Huang, Wei-Long Chen</i>	
Construction of Chitosan/Poly(vinyl alcohol)/Poly(ethylene oxide) Scaffolds Via Electrospinning Technology	370
<i>J. H. Tu, Y. J. Tsai, Z. Y. Wu, C. L. Chung</i>	
Perovskite $\text{La}_{0.8}\text{Sr}_{0.2}\text{Mn}_{1-x}\text{Ni}_x\text{O}_3$ Nanofibers Of Electrospinning	372
<i>Y. J. Zhu, K. K. Chen, C. L. Chung, J. D. Lin</i>	

Analysis of Au and Ru Passivation Layers Deposited via Electroless Plating for Low-Temperature Cu-Cu Bonding	374
<i>Byeongchan Go, Hoohwan Lee, Keiyu Komamura, Takanori Kishida, Sarah Eunkyung Kim</i>	
Machine Learning-Based Surrogate Model of Thermal Simulation for Heat Sink Design	376
<i>Seongju Kim, Jimin Kwon</i>	
New Concept of Intrinsically Switched Tunable Bandpass Filter Using Multi-band Resonators	378
<i>Akehito Shiotake, Hiroki Matsuura, Junichiro Matsuki, Koji Wada</i>	
Fan-out RDL technology development for shuttle service	380
<i>Chen-Chun Yu, Yi-Shu Chen, Yuan-Chang Lee, Huan-Chun Fu, Liang-Cyuan Chang, Yu-Fang Chen</i> <i>I-Hsing Lin, Chia-Wen Chiang, Shih-Cheng You, Pei-Jou Fang, Chia-Wen Fan, Kuan-Chu Wu</i> <i>Wan-Hsin Chen, Ying-Ju Chen, Hsiang-Hung Chang, Chin-Hung Wang, Wei-Chung Lo, Shih-Chieh Chang</i>	
Development of AlN Fillers for Composite Resins with High Thermal Conductivity and Low Bond-Line Thickness	382
<i>Yusaku Imasaku, Atushi Sanagawa, Isao Masada, Go Hamasaka, Yukihiro Kanechika</i>	
Investigation of Electrical and Reliability Properties in Nanotwinned Sintered Joints	384
<i>Shin-Yi Huang, Po-Kai Chiu, Yung-Min Hsieh, Yu-Hua Wu, Fan-Yi Ouyang</i>	
Warpage of Organic RDL Interposers in 3D Heterogeneous WLP via a Chip-First Hybrid Bonding Process	386
<i>Ching-Feng Yu, Chao-Kai Hsu, Chih-Cheng Hsiao</i>	
Performance analysis of Au and Ag metallization for silicon-adapted LTCC horn antenna structures	388
<i>C. Kleinholz, B. Müller, A. Schulz, M. Fischer, C. Tschoban, K.-F. Becker, M. Schneider-Ramelow</i> <i>J. Müller</i>	
Low-Temperature Curable Photo-Definable Polyimide and Its Application as a Sealing Material for RF-MEMS	390
<i>Susumu Tanaka, Tomoki Sakai, Yumiko Okuda, Hitoshi Araki</i>	
VUV-induced Surface Activation for Cu/SiO ₂ Hybrid Bonding: Effect of H ₂ Concentration in H ₂ /H ₂ O Mixed Atmosphere	392
<i>K. Nishio, K. Wu, A. Shimizu, S. Endo, A. Shimamoto</i>	
Development of Sintering Silver Paste Enabling Short Time Sintering in Non-Pressure Silver Bonding	394
<i>Daisuke Tomotoshi, Takamichi Mori</i>	
Fabrication of Cu Nanocrystalline by PR Electroplating Method and Influence of Additives on Grain Size	396
<i>Masato Tsuchiya, Yuma Sato, Katsuji Nakamura</i>	
Development of Electromagnetic Shielding Material Testing Technology	398
<i>Yen-Ting Lu, Sung-Mao Wu, Yu-Zhi Ma, Guan-Yu Hong</i>	
Cu Electrodeposition with a Single Additive for Bottom-Up Filling of TSVs	400
<i>Seolim Yoon, Hui Won Eom, Haejin Kwak, Yun Ha, Myung Jun Kim</i>	
Defect-Free TGV Filling via Cu Electrodeposition with Ammonium-based Additives	402
<i>Hui Won Eom, Seonjin Yang, Haejin Kwak, Dong Kun Cha, Myung Jun Kim</i>	

Comparative Evaluation of Sputtered Transition-Metal Thin Films on Glass Substrate for Hydrogen Evolution Reaction	404
<i>Wei-Chen Tsu, Hao-Lin Hsu, Jun Mizuno</i>	
Microstructure Modeling, Prediction, and Verification of Cu-Ag Sintered Paste for Die-attach Based on the Quartet Structure Generation Set (QSGS) Algorithm	406
<i>Xinyue Wang, Wenting Liu, Letao Bian, Zhoudong Yang, Guoqi Zhang, Jing Zhang, Kim S. Siow, Pan Liu</i>	
Interfacial Corrosion Behavior Analysis of Sintered Silver and Sintered Copper Joints for Power Electronics Packaging	408
<i>Letao Bian, Xinyue Wang, Jing Zhang, Jianhao Wang, Guoqi Zhang, Kim S. Siow, Pan Liu</i>	
Automatic PCB Component Placement via GNN-Guided Similarity Retrieval Coupled with GAN-Based Completion	410
<i>Hiroki Yonekura, Tomio Echigo</i>	
Mechanical Characterization of Sintered Silver Paste via Nanoindentation for Advanced Packaging in Power Electronics	412
<i>Qihang Zong, Chenshan Gao, Fred Ouyang, Huaiyu Ye</i>	
Wafer Bonding Void Investigation with SiN Dielectric Film	414
<i>Yeong-Jyh Lin, Chen-Yang Chou, Wei-You Hong</i>	
System-Level Fast Optimization Method for High-Speed Circuits Based on Electro-Thermal Equivalent Modeling	416
<i>Cheng-Hsuan Liu, Sung-Mao Wu</i>	
Yield-Limiting Mechanisms Governed by Dicing and Bonding Conditions in Organic Hybrid Bonding	418
<i>Zhao-Ze Jiang, Alexis Angelo R. Garcia, Chih-Jing Hsu, Chen-Hung Lee, Po-Hsiang Wang, Wang-Chia Ching, Chen-Chung Hung, Jen-Chieh Kao, Yung-I Yeh</i>	
High Throughput Silver-based Metal-organic Decomposition with Spray Coating for Package-level EMI Shielding	420
<i>M.-H. Chen, W.-H. Wang, C. -L. Huang, J.-C. Kao, Y.-E Yeh</i>	
Room Temperature Direct Bonding of Lithium Niobate Wafers With Different Orientations	422
<i>Y. Katoda, J. Nakamura, R. Takigawa</i>	
High-efficiency Cleaning for Particle Removal Applied in the CoW Hybrid Bonding Process	424
<i>Chih-Jing Hsu, Zhao-Ze Jiang, Che-Ming Hsu, Chen-Hung Lee, Jen-Chieh Kao, Yung-I Yeh</i>	
Effect of Pre-Annealing Time of Ti/Ag Metallized Cu Substrate on Ag–Ag Direct Bonding for SiC Die Attach	426
<i>Minseo Kim, Sangmin Lee, Chuantong Chen, Seungmin Cho, Myung Sik Choi, Soongkeun Hyun, Katsuaki Suganuma</i>	
Development of LCP membrane-based Low Dielectric Laminate for High-Frequency High-Speed Communications	428
<i>Seong-Dae Park, Yejun Ban, Bo-young Kim, Myong-Jae Yoo, Hyunseung Yang</i>	
Reliability Analysis of Copper Paste Joints between Ni/Au-Coated SiC Chips and AMB Substrates during High-Temperature Aging	430
<i>Seungmin Cho, Chuantong Chen, Sangmin Lee, Fupeng Huo, Minseo Kim, Katsuaki Suganuma</i>	

ANN Surrogate Model for Signal Integrity Prediction of FCBGA	432
<i>Soojin Lim, SoYoung Kim</i>	
GNN-Based Early Power Integrity Estimation for PDN Design	434
<i>Seonghyun Park, SoYoung Kim</i>	
Surrogate Model for Junction Temperature Prediction for High-Performance Computing Chips Using Direct-to-Chip Liquid Cooling	436
<i>Jiaxin Weng, Yusuo Guo, Xiong Xiao, Jiapeng Huang, ZhiZhen Wang, Shenglin Ma</i>	
Study on the High-Frequency Electrical Performance Degradation mechanism of RF TGV Transmission Structures During Temperature Cycling Tests Under High-Power and High-Temperature Conditions	438
<i>Zhilin Wei, Luming Chen, Chunlei Li, Hai Yuan, Shuwei He, Shenglin Ma</i>	
Interfacial Chemistry-Driven Reliability Enhancement in Air-Cured Bimodal Cu-Filled Conductive Pastes	440
<i>Ayumi Uchida, Masahiro Inoue</i>	
Tailoring Electrical Properties of Printed Stretchable Wires via Binder Molecular Design for Electrically Conductive Pastes	442
<i>Togo Hatori, Haruya Okamura, Masahiro Inoue</i>	
Effect of Structural Factors in Enhancing Dynamic Percolation of Multi-walled Carbon-nanotube-filled Conductive Pastes	444
<i>Tomoya Hanada, Masahiro Inoue</i>	
Design Study of Next-Generation Hybrid Bonding Processes for Chip-Scale Integration	446
<i>Hideki Kitada, Koharu Yuzawa, Tadashi Fukuda, Takayuki Ohba</i>	
Physics-Informed Small-Sample Neural Network for Submicron Etch Profiles Predicting in SF ₆ /O ₂ /SiF ₄ Reactive Ion Etching	448
<i>Yikang Ding, Bo Wen, Lang Chen, Yihui Cheng, Chong Chen, Chi Zhang, Pan Zhang, Wei Wang, Yufeng Jin</i>	